

GP1S74PJ000F

Gap : 5mm Slit : 0.5mm
Phototransistor Output,
Snap-in fixing
Transmissive Photointerrupter with
Connector



■ Description

GP1S74PJ000F is a standard, phototransistor output, transmissive photointerrupter with opposing emitter and detector in a case, providing non-contact sensing. For this family of devices, the emitter and detector are inserted in a case, and a 3-pin connector is included to allow remote-mount or off-board designs.

■ Features

1. Transmissive with phototransistor output
2. Highlights :
 - Special position hooks compatible with 3 different plate thicknesses (1.0, 1.2, 1.6mm)
 - Snap insertion
3. Key Parameters :
 - Gap Width : 5mm
 - Slit Width (detector side): 0.5mm
 - Package : 17×12.8×8mm (without connector and hooks)
 - Connector : Tyco Electronics AMP K.K. (PN : 292133-3)
4. Lead free and RoHS directive compliant

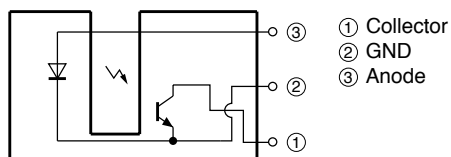
■ Agency approvals/Compliance

1. Compliant with RoHS directive

■ Applications

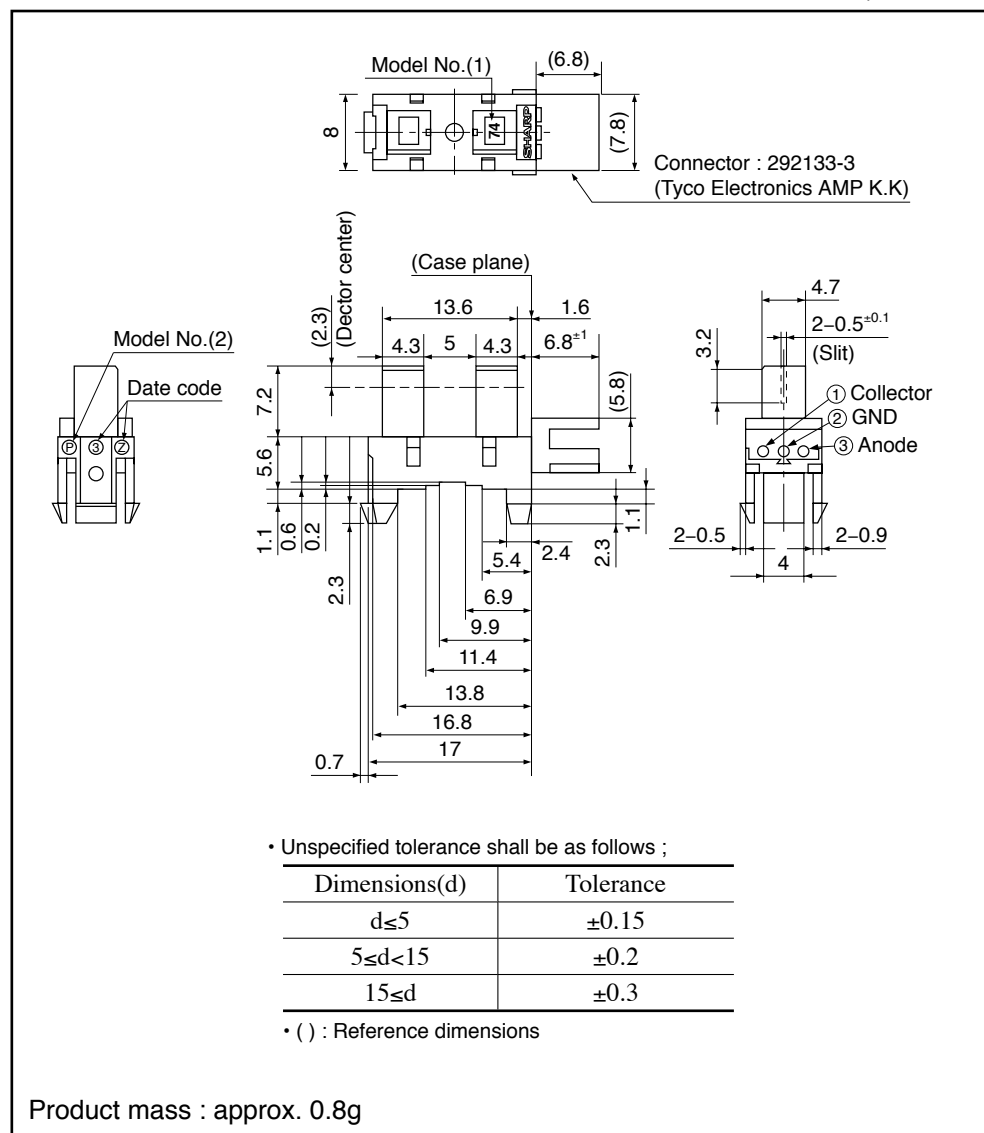
1. General purpose detection of object presence or motion.
2. Example : PPC, FAX, Printer

Internal Connection Diagram



Outline Dimensions

(Unit : mm)



Connector terminal plating material : Sn

Date code (2 digit)

1st digit		2nd digit	
Year of production		Month of production	
A.D.	Mark	Month	Mark
2000	0	1	1
2001	1	2	2
2002	2	3	3
2003	3	4	4
2004	4	5	5
2005	5	6	6
2006	6	7	7
2007	7	8	8
2008	8	9	9
2009	9	10	X
2010	0	11	Y
:	:	12	Z

repeats in a 10 year cycle

Country of origin

Japan or Philippines

(Indicated on the packing case)

■ Absolute Maximum Ratings

(T_a=25°C)

	Parameter	Symbol	Rating	Unit
Input	*1 Forward current	I _F	50	mA
	*1, 2 Peak forward current	I _{FM}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	V _{CEO}	35	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	I _C	20	mA
	*1 Collector power dissipation	P _C	75	mW
*3 Operating temperature		T _{opr}	−25 to +85	°C
*3 Storage temperature		T _{stg}	−40 to +85	°C

*1 Refer to Fig. 1, 2, 3

*2 Pulse width ≤ 100μs, Duty ratio=0.01

*3 The connector should be plugged in/out at normal temperature.

■ Electro-optical Characteristics

(T_a=25°C)

	Parameter		Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V _F	I _F =20mA	–	1.2	1.4	V
	Peak forward voltage		V _{FM}	I _{FM} =0.5A	–	3	4	V
	Reverse current		I _R	V _R =3V	–	–	10	μA
Output	Collector dark current		I _{CEO}	V _{CE} =20V	–	1	100	nA
Transfer charac- teristics	Collector current		I _C	V _{CE} =5V, I _F =20mA	0.5	–	15	mA
	Collector-emitter saturation voltage		V _{CE(sat)}	I _F =40mA, I _C =0.5mA	–	–	0.4	V
	Response time	Rise time	t _r	V _{CE} =2V, I _C =2mA, R _L =100Ω	–	3	15	μs
		Fall time	t _f		–	4	20	

Fig.1 Forward Current vs. Ambient Temperature

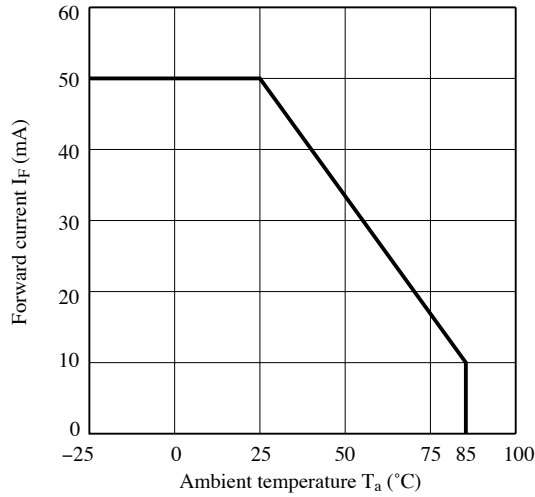


Fig.2 Collector Power Dissipation vs. Ambient Temperature

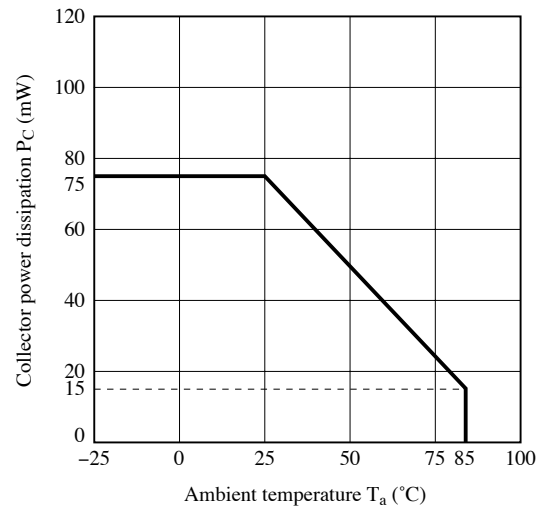


Fig.3 Peak Forward Current vs. Duty Ratio

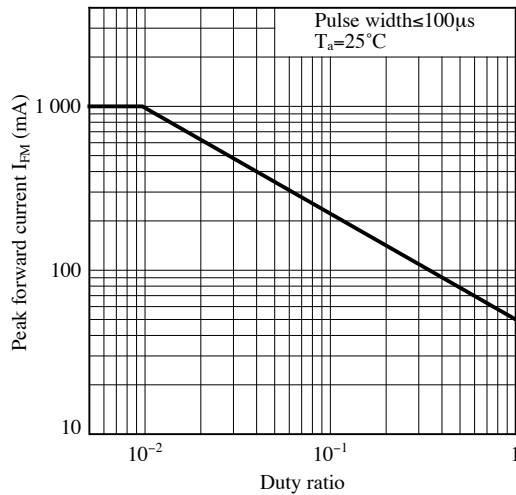


Fig.4 Forward Current vs. Forward Voltage

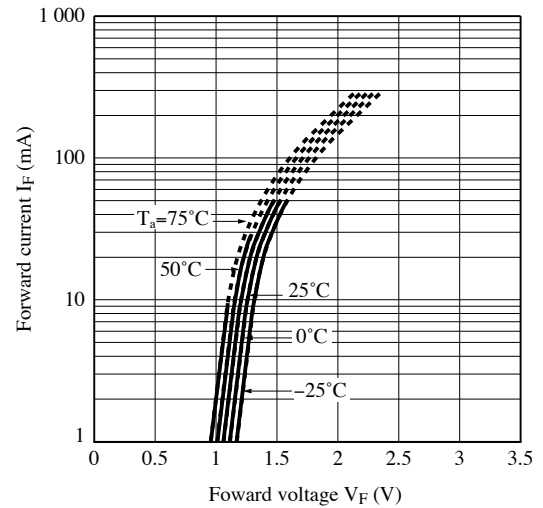


Fig.5 Collector Current vs. Forward Current

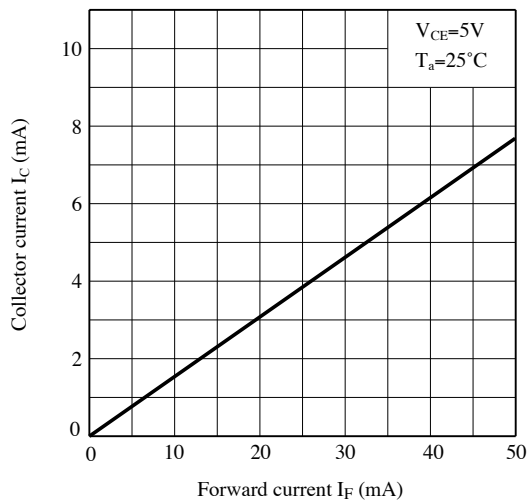


Fig.6 Collector Current vs. Collector-emitter Voltage

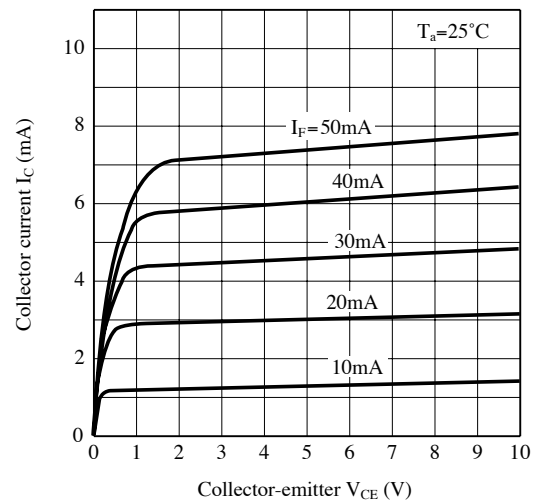


Fig.7 Collector Current vs. Ambient Temperature

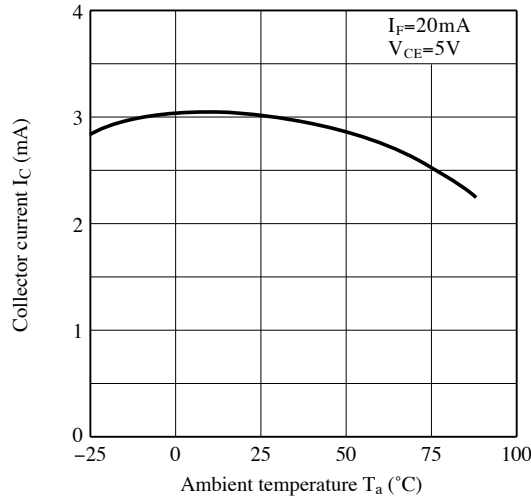


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

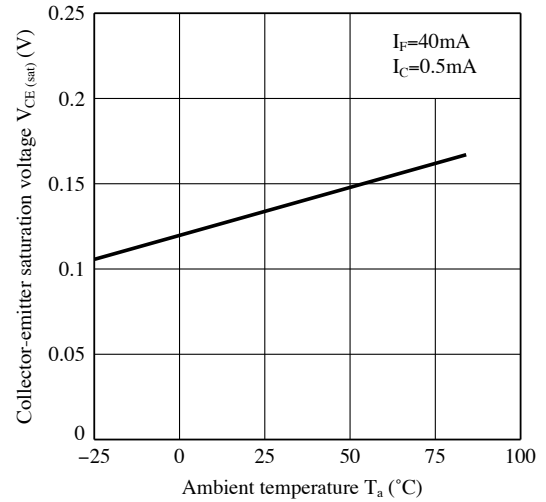


Fig.9 Response Time vs. Load Resistance

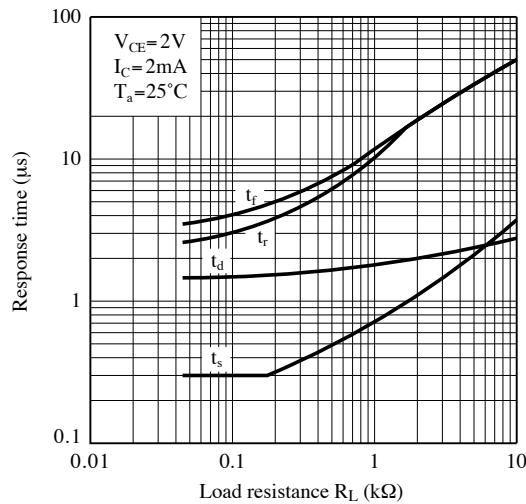


Fig.10 Test Circuit for Response Time

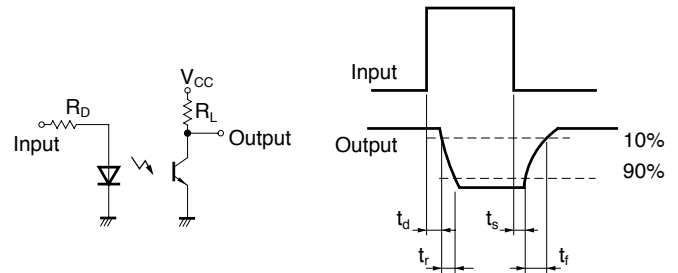


Fig.11 Frequency Response

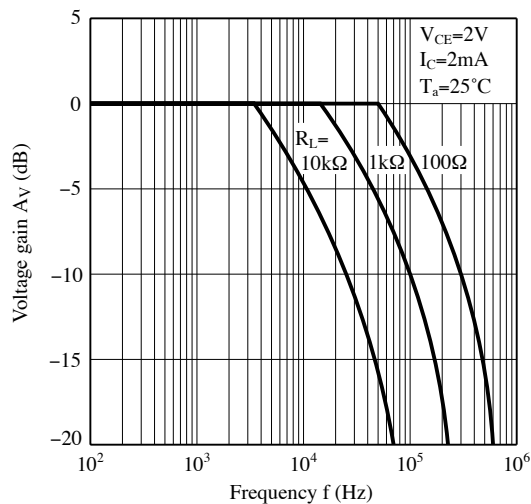


Fig.12 Collector Dark Current vs. Ambient Temperature

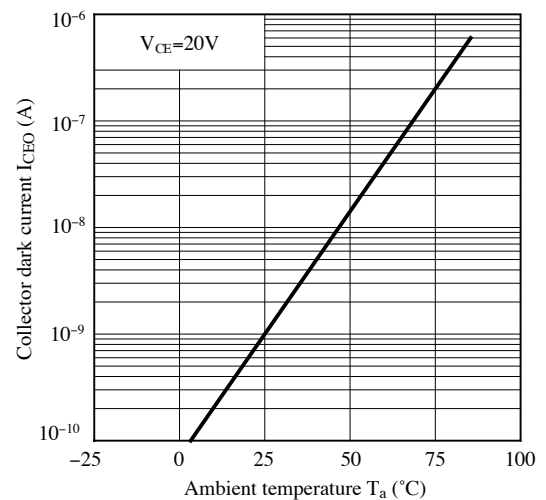


Fig.13 Detecting Position Characteristics (1)

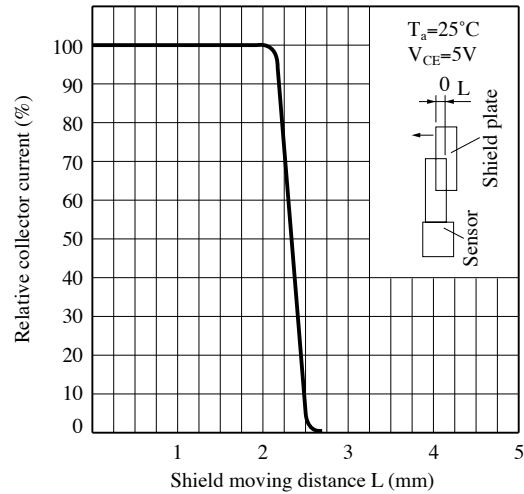
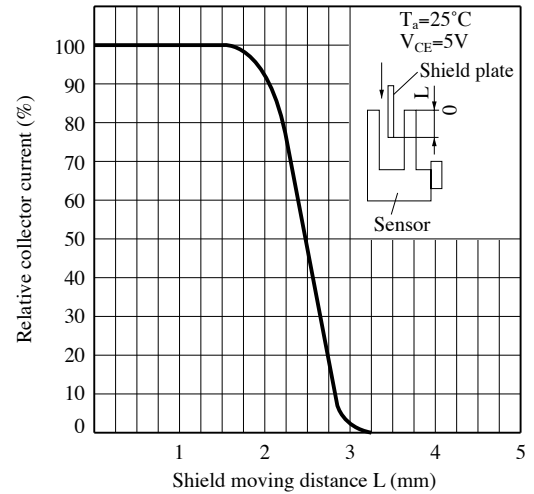


Fig.14 Detecting Position Characteristics (2)



Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

■ Design Considerations

● Design guide

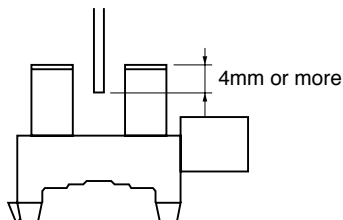
1) Prevention of detection error

To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

2) Position of opaque board

Opaque board shall be installed at place 4mm or more from the top of elements.

(Example)



This product is not designed against irradiation and incorporates non-coherent IRED.

● Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

● Parts

This product is assembled using the below parts.

• Photodetector (qty. : 1)

Category	Material	Maximum Sensitivity wavelength (nm)	Sensitivity wavelength (nm)	Response time (μs)
Phototransistor	Silicon (Si)	930	400 to 1 200	3

• Photo emitter (qty. : 1)

Category	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared emitting diode (non-coherent)	Gallium arsenide (GaAs)	950	0.3

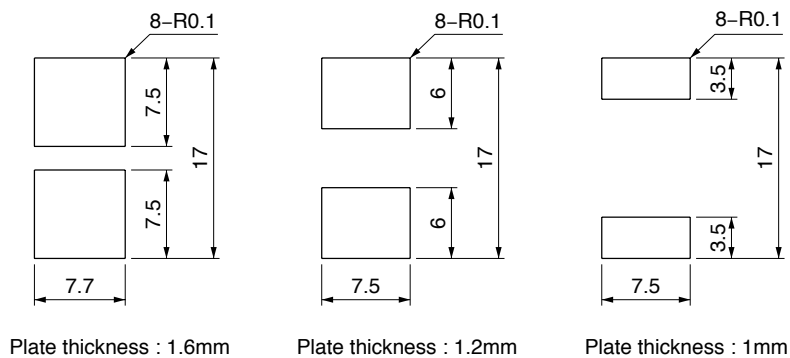
• Material

Case	Lead frame	Connector terminal finish
Black polycarbonate resin (UL94 V-2)	42Alloys (No plating)	Sn plating

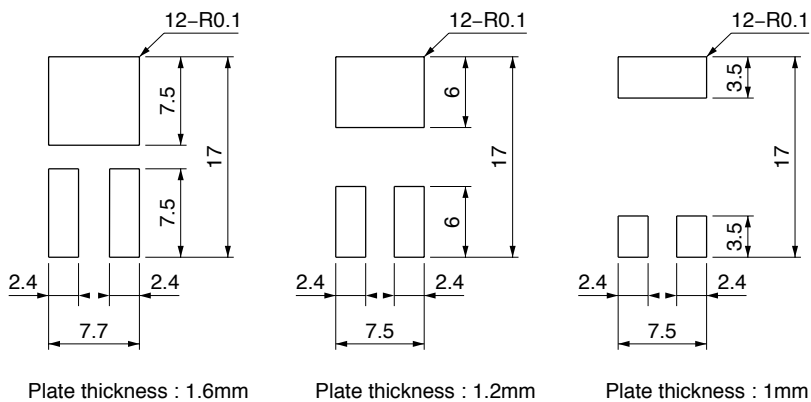
● Recommended Installation Hole drawing

- 1) We recommend to fix the product at punching side on the fixing plate (metal plate).
- 2) Please decide the final dimensions at your side after confirmation by the actual applications. Because mounting efficiency and mounted stabilization are dependent on mounting hole corner curve and punched state.
- 3) Tolerance shall be $\pm 0.1\text{mm}$

Normal type



Reverse-insertion prevention type



■ Manufacturing Guidelines**● Notes of cleaning**

Please carry out neither the immersion cleaning nor the ultrasonic cleaning to avoid the solvent residue inside the case.

When necessary, dust and stain shall clean by air-blow or wipe off by soft cloth soaked in cleaning agent. The cleaning agent used to wipe off must use only the following kind. Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

● Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

■ Package specification

● Case package

Package materials

Anti-static plastic bag : Polyethylene

Moltopren : Urethane

Partition : Corrugated fiberboard

Packing case : Corrugated fiberboard

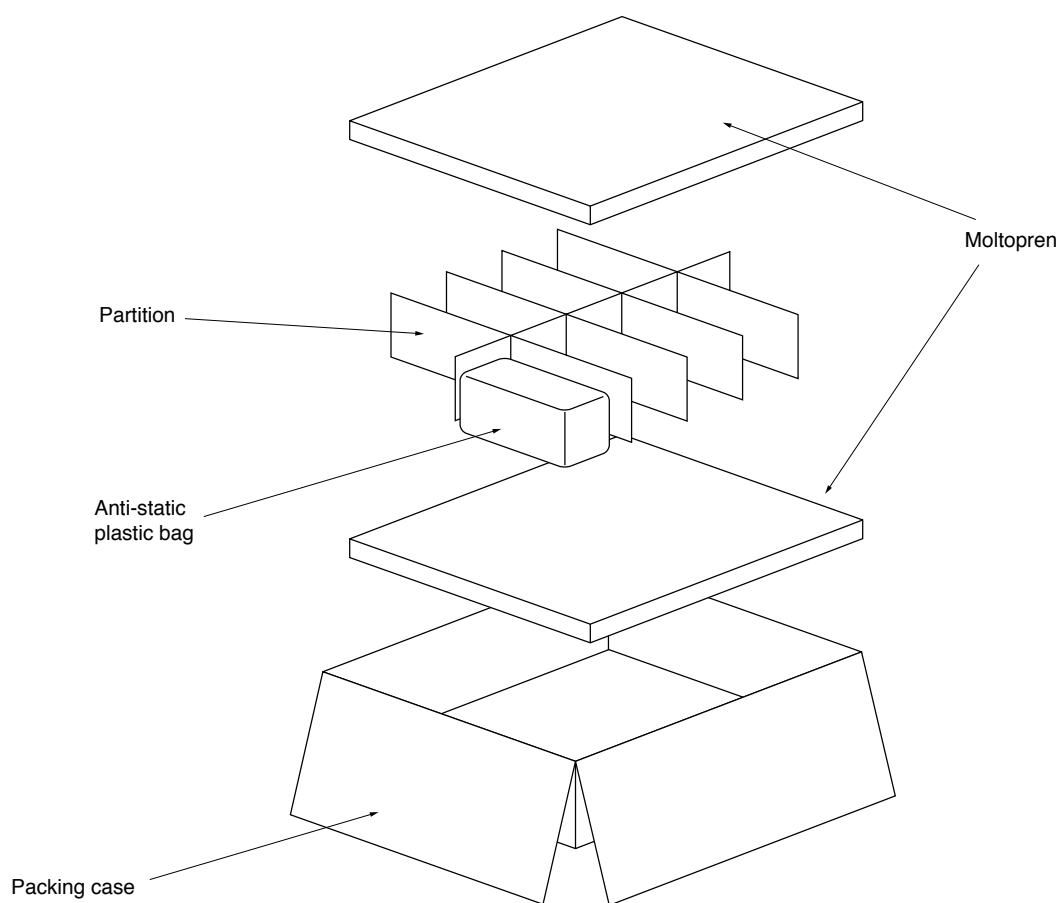
Package method

100 pcs of products shall be packaged in a plastic bag, Ends shall be sealed by stapler. The bottom of the packing case is covered with moltopren, and the partition is set in the packing case. Each partition should have 1 plastic bag.

The 10 plastic bags containing a product are put in the packing case.

Moltopren should be located after all product are settled (1 packing contains 1 000 pcs).

Packing composition



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